

Amendment and Response Under 37 C.F.R. 1.116

Applicant: Edmund Riedl

Serial No.: 10/551,745

Filed: March 19, 2007

Docket No.: I431.131.101/FIN421PCT/US

Title: DIFFUSION SOLDERED SEMICONDUCTOR DEVICE (As Amended)

REMARKS

The following remarks are made in response to the Final Office Action mailed March 29, 2010. Claims 15-25 have been withdrawn from consideration. Claims 26-28 and 30-36 were rejected. Claim 29 has been objected to. With this Response, claims 26 and 30 have been amended. Claims 26-36 remain pending in the application and are presented for reconsideration and allowance.

Claim Rejections under 35 U.S.C. § 102

Claims 26, 27 and 30 were rejected under 35 U.S.C. 102(b) as allegedly being anticipated by Sato (US 6,083,770). Applicants respectfully traverse these rejections.

Claims 26 and 30 have been amended to more clearly recite the structure of the claimed semiconductor devices. Claims 26 and 30 have been amended to recite first and second diffusion-soldered joints are from respective first and second diffusion-soldering alloys having different melting points.

It is well accepted that, to anticipate a claim, the cited reference must disclose each claim element. MPEP 2131. The Office Action fails to identify disclosures in Sato of the diffusion-soldering alloys recited in claims 26 and 30. As such, claims 26, 27 and 30 are believed to be in condition for allowance.

Claim Rejections under 35 U.S.C. § 103

Claims 28, and 31-36 were rejected under 35 U.S.C. 103(a) as being unpatentable over Sato et al. in view of additional references. These claims all depend on either claim 26 or claim 30 and are therefore allowable for at least the same reasons.

Allowable Subject Matter

The Examiner objected to claim 29 for being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all limitations of the base claim and any intervening claims. The Examiner's acknowledgment of the allowable subject matter is

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appreciated. However, as noted above, claim 26 is believed to be proper for allowance. Claim 29 is therefore allowable for at least the same reasons.

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CONCLUSION

In view of the above, Applicant respectfully submits that all of the pending claims are in form for allowance. Therefore, reconsideration and withdrawal of the rejections and allowance of the claims are respectfully requested.

No fees are required under 37 C.F.R. 1.16(h)(i). However, if such fees are required, the Patent Office is hereby authorized to charge Deposit Account No. 50-0471.

Please consider this a Petition for Extension of Time for a sufficient number of months to enter these papers, if appropriate. At any time during the pendency of this application, please charge any additional fees or credit overpayment to Deposit Account No. 500471.

The Examiner is invited to contact the Applicant's representative at the below-listed telephone numbers to facilitate prosecution of this application.

Any inquiry regarding this Amendment and Response should be directed to Mark L. Gleason at Telephone No. (612) 767-2503, Facsimile No. (612) 573-2005. In addition, all correspondence should continue to be directed to the following address:

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Respectfully submitted,

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